

HM25SDN03Q

Dual Asymmetric N-Channel Enhancement Mode MOSFET

➤ Features

VDS	VGS	RDS(ON) Typ.	ID
30V	±20V	12mR@10V	25A
		11 mR@4V5	

➤ Description

This device uses advanced trench technology to provide excellent RDS(ON) and low gate charge. This device is suitable for use as a load switch or in PWM applications.

➤ Applications

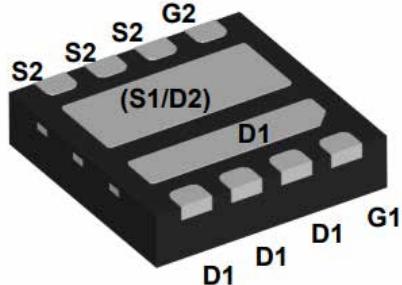
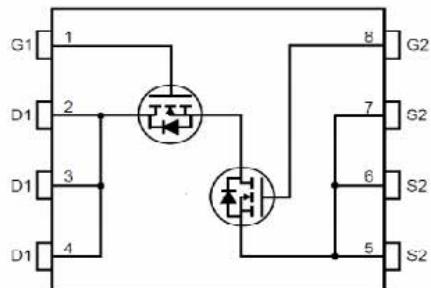
- Power Management in notebook computer
- Portable Equipment
- Battery Powered Systems

➤ Ordering Information

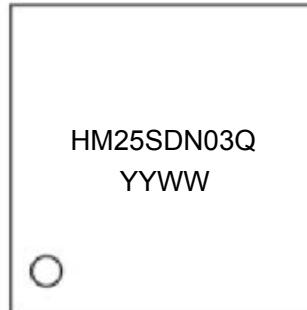
Device	Package	Shipping
HM25SDN03Q	DFN3X3	5000/Reel

➤ Pin configuration

Top view



Bottom View



Marking

➤ **Absolute Maximum Ratings($T_A=25^\circ\text{C}$ unless otherwise noted)**

Symbol	Parameter	Ratings	Unit	
V_{DSS}	Drain-to-Source Voltage	30	V	
V_{GSS}	Gate-to-Source Voltage	± 20	V	
I_D	Continuous Drain Current	$TC=25^\circ\text{C}$	25	A
		$TC=100^\circ\text{C}$	17	A
I_{DM}	Pulsed Drain Current ^b	75	A	
I_{DSM}	Continuous Drain Current ^a	$TA=25^\circ\text{C}$	14	A
		$TA=70^\circ\text{C}$	9	A
P_D	Power Dissipation ^c	$TC=25^\circ\text{C}$	25	W
		$TC=100^\circ\text{C}$	10	W
P_{DSM}	Power Dissipation ^a	$TA=25^\circ\text{C}$	2.5	W
		$TA=70^\circ\text{C}$	0.9	W
I_{AS}	Avalanche Current	25	A	
E_{AS}	Avalanche Energy, $L=0.05\text{mH}$	16	mJ	
T_J	Operation junction temperature	-55 to 150	$^\circ\text{C}$	
T_{STG}	Storage temperature range	-55 to 150	$^\circ\text{C}$	

➤ **Thermal Resistance Ratings($T_A=25^\circ\text{C}$ unless otherwise noted)**

Symbol	Parameter	Typical	Maximum	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a		55	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance		6	

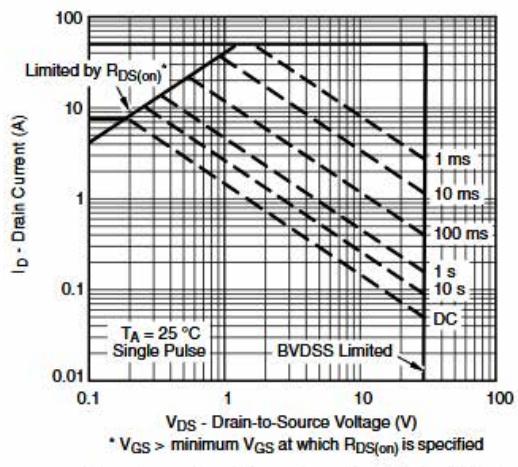
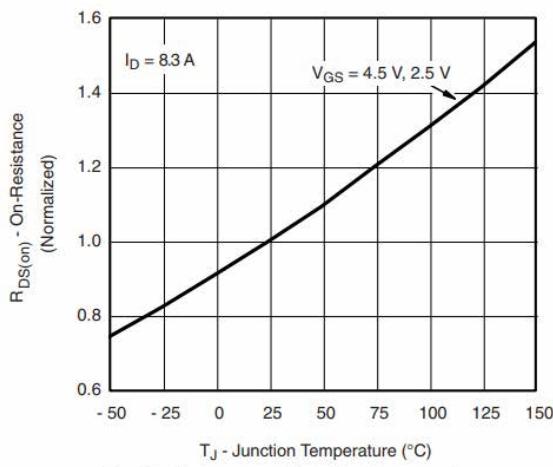
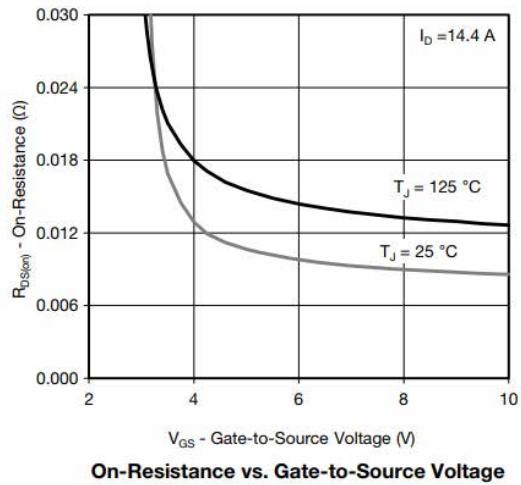
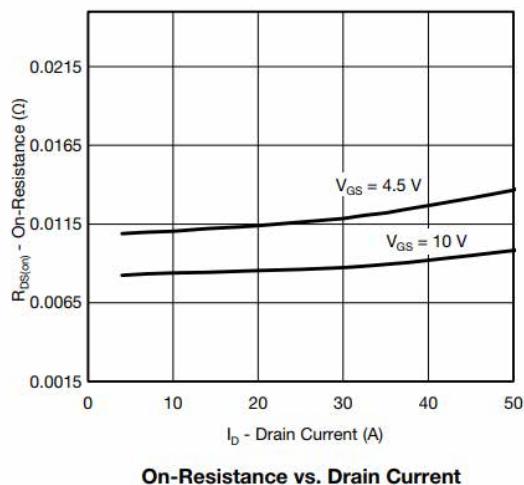
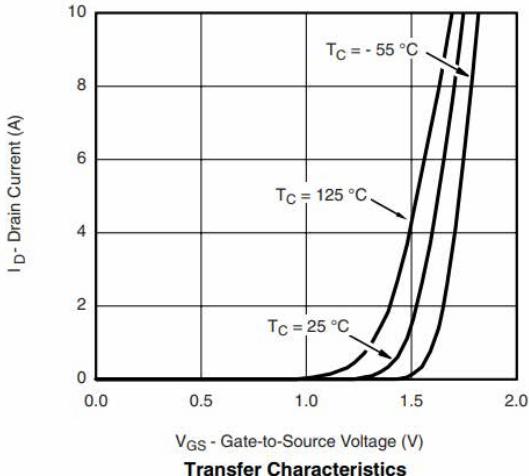
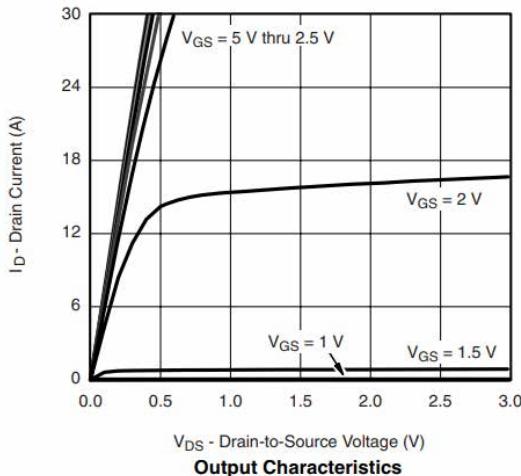
Note:

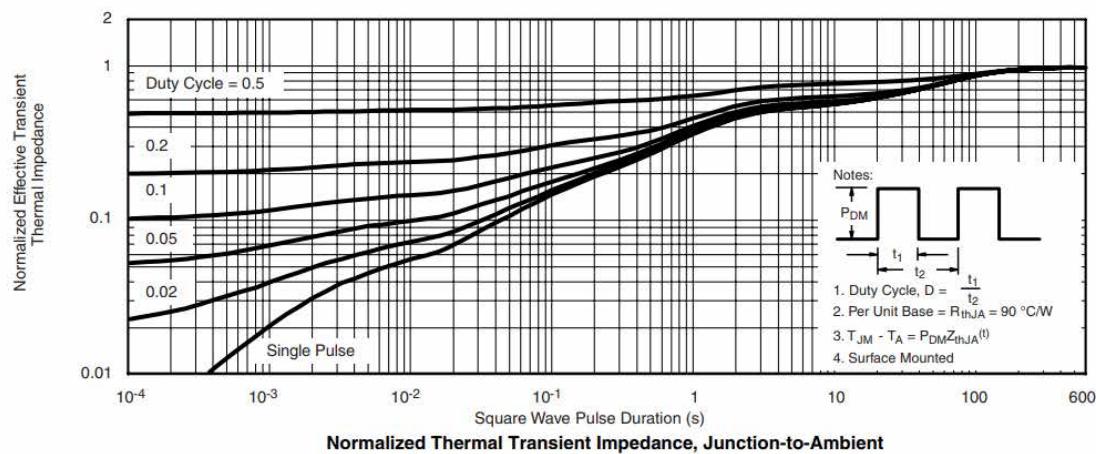
- a. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper,in a still air environment with $TA=25^\circ\text{C}$.The value in any given application depends on the user is specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on $T_J(\text{MAX})=150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

➤ **Electronics Characteristics($T_A=25^\circ C$ unless otherwise noted)**

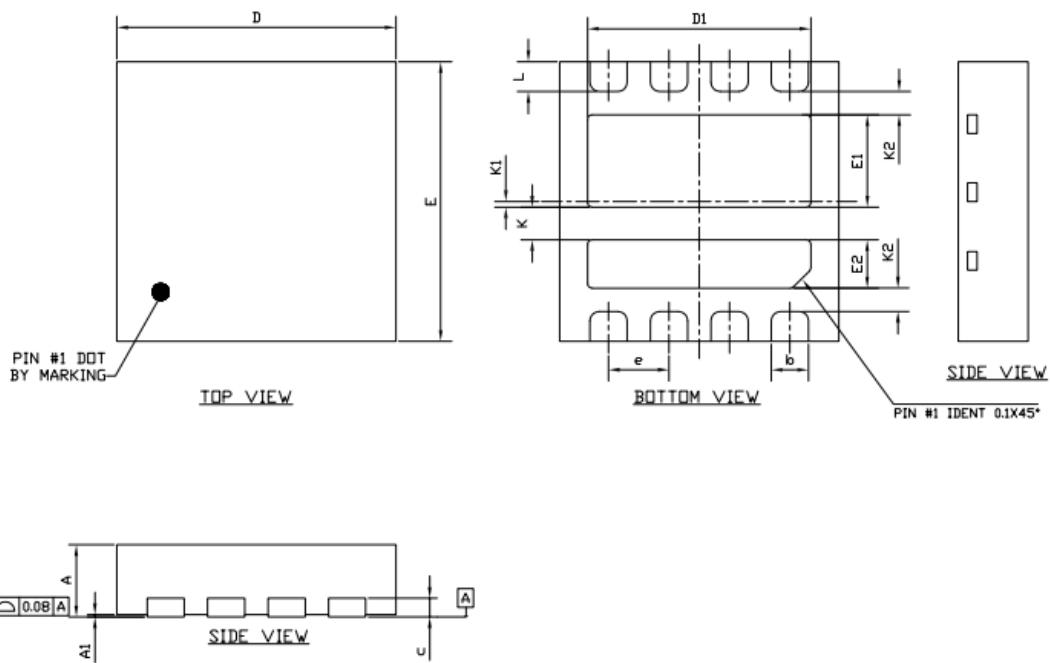
Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$VGS=0V, ID=250\mu A$	30			V
$V_{GS(th)}$	Gate Threshold Voltage	$VDS=VGS, ID=250\mu A$	1.0		2.5	V
$R_{DS(on)}$	Drain-Source On-Resistance	$VGS=10V, ID=20A$			12	mR
		$VGS=4.5V, ID=10A$			14	
I_{DSS}	Zero Gate Voltage Drain Current	$VDS=30V, VGS=0V$			1	uA
I_{GSS}	Gate-Source leak current	$VGS=\pm 20V, VDS=0V$			± 100	nA
V_{SD}	Forward Voltage	$VGS=0V, IS=0.5A$		0.8	1.3	V
G_{FS}	Transconductance	$VDS=15V, ID=10A$		55		S
C_{iss}	Input Capacitance	$VDS=15V, VGS=0V, f=1MHz$		650		pF
C_{oss}	Output Capacitance			220		
C_{rss}	Reverse Transfer Capacitance			105		
$T_{D(ON)}$	Turn-on delay time	$VGS=10V,$ $VDS=15V, RG=3R, RL=2.3R$		12		ns
Tr	Rise time			6		
$T_{D(OFF)}$	Turn-off delay time			22		
Tf	Fall time			9		
Qg	Total Gate charge	$VGS=10V, VDS=15V, ID=12A$		18		nC
Qgs	Gate to Source charge			2.3		
Qgd	Gate to Drain charge			3.2		

➤ **Typical Characteristics**($T_A=25^\circ\text{C}$ unless otherwise noted)





➤ Package Information



DFN3X3

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0.028	0.030	0.032
A1	0.00	---	0.05	0.000	---	0.002
c	0.203 REF.					
b	0.35	0.40	0.45	0.014	0.016	0.018
D	2.90	3.00	3.10	0.114	0.118	0.122
D1	2.30	2.40	2.50	0.090	0.094	0.098
E	2.90	3.00	3.10	0.114	0.118	0.122
E1	0.89	0.99	1.09	0.035	0.039	0.043
E2	0.42	0.52	0.62	0.016	0.020	0.024
e	0.65 BSC			0.026 BSC		
L	0.27	0.32	0.37	0.011	0.013	0.015
K	0.35 REF.					
K1	0.06 REF.					
K2	0.25 REF.					